

## SSC8030GN2

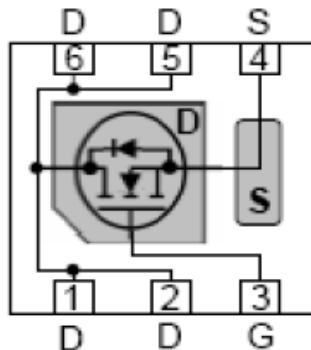
### N-Channel Enhancement Mode MOSFET

#### ➤ Features

VDS	VGS	RDS(on) Typ.	ID
30V	±20V	8.5mR@10V	10A
		10.5mR@4V5	

#### ➤ Pin configuration

Top view



#### ➤ Description

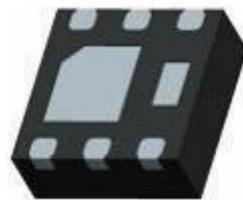
This device uses advanced trench technology to provide excellent RDS(on) and low gate charge. This device is suitable for use as a load switch or in PWM applications.

#### ➤ Applications

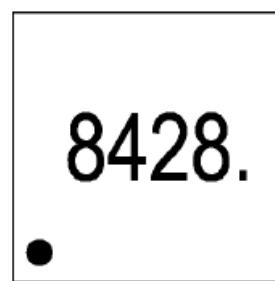
- Load Switch
- PC/NB
- DCDC conversion

#### ➤ Ordering Information

Device	Package	Shipping
SSC8030GN2	DFN2x2	3000/Reel



Bottom View



Marking

➤ **Absolute Maximum Ratings( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	30	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>a</sup>	10	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	41	A
$P_D$	Power Dissipation <sup>c</sup>	5	W
$P_{DSM}$	Power Dissipation <sup>a</sup>	2.4	W
$T_J$	Operation junction temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage temperature range	-55 to 150	$^\circ\text{C}$

➤ **Thermal Resistance Ratings( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>		60	$^\circ\text{C/W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance		30	

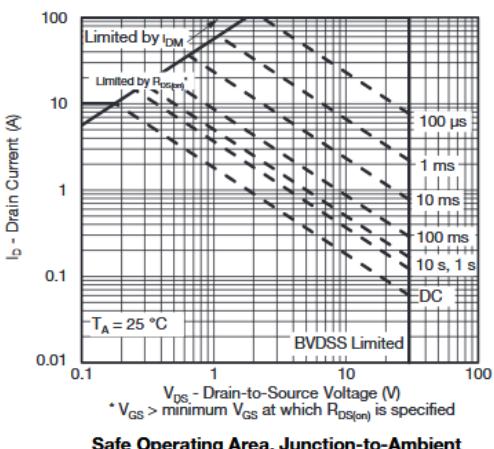
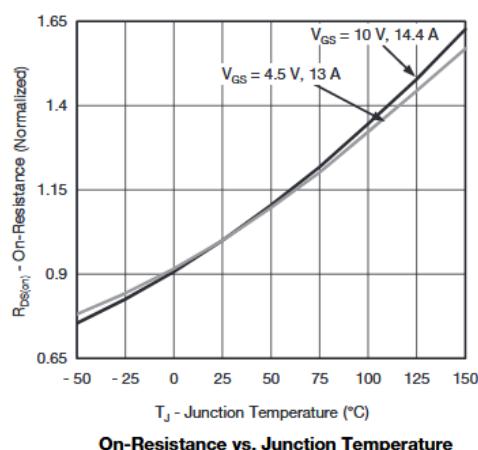
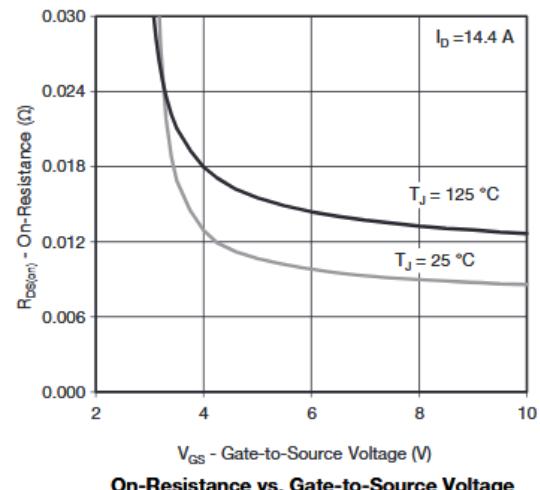
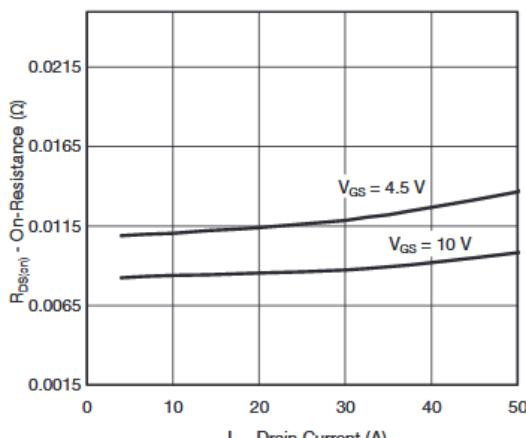
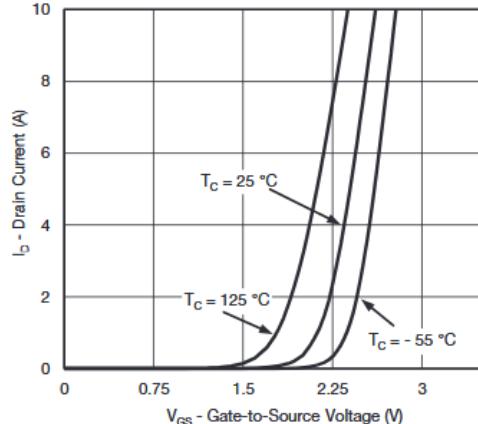
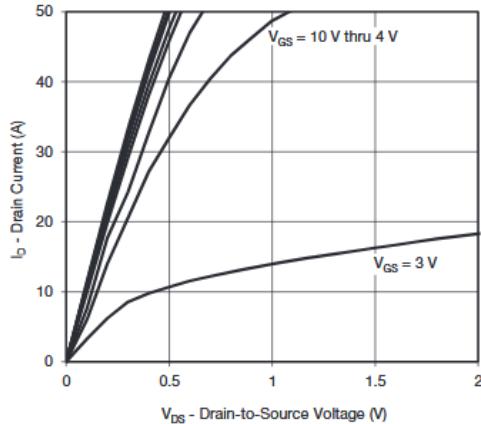
Note:

- a. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper,in a still air environment with  $T_A=25^\circ\text{C}$ .The value in any given application depends on the user specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

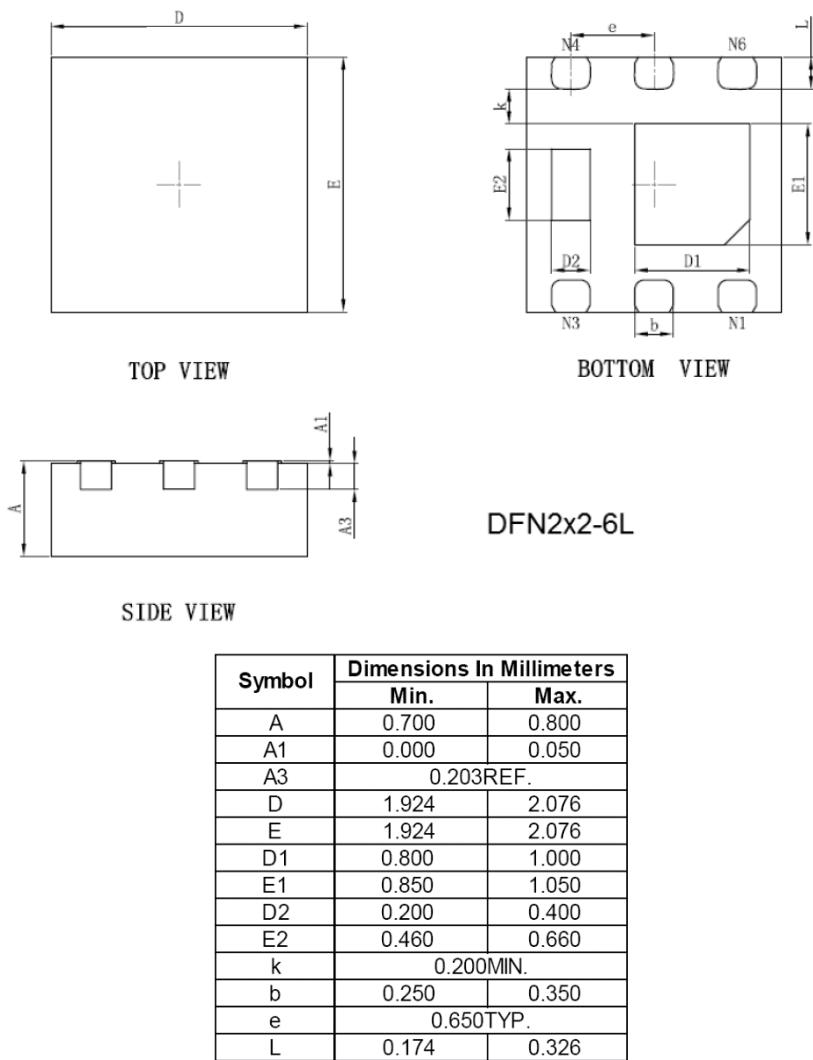
➤ Electronics Characteristics( $T_A=25^\circ C$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$VGS=0V, ID=250\mu A$	30			V
$V_{GS(th)}$	Gate Threshold Voltage	$VDS=VGS, ID=250\mu A$	1	1.5	3	V
$R_{DS(on)}$	Drain-Source On-Resistance	$VGS=10V, ID=10A$		8.5	10.5	mR
		$VGS=4.5V, ID=8A$		10.5	14	
$I_{DSS}$	Zero Gate Voltage Drain Current	$VDS=24V, VGS=0V$			1	$\mu A$
$I_{GSS}$	Gate-Source leak current	$VGS=\pm 20V, VDS=0V$			$\pm 100$	nA
$G_{FS}$	Transconductance	$VDS=15V, ID=8A$		16		S
$V_{SD}$	Forward Voltage	$VGS=0V, IS=1A$		0.8	1.5	V
$C_{iss}$	Input Capacitance	$VDS=15V, VGS=0V, f=1MHz$		1130		pF
$C_{oss}$	Output Capacitance			200		
$C_{rss}$	Reverse Transfer Capacitance			105		
$T_{D(ON)}$	Turn-on delay time	$VGS=10V,$ $VDS=15V, RL=2.3R, RG=3R$		18		ns
$T_r$	Rise Time			11		
$T_{D(OFF)}$	Turn-off delay time			70		
$T_f$	Fall Time			16		
$Q_g$	Total Gate charge	$VGS=10V, VDS=10V, ID=4A$		24		nC
$Q_{gs}$	Gate to Source charge			3		
$Q_{gd}$	Gate to Drain charge			5		

➤ **Typical Characteristics**( $T_A=25^\circ\text{C}$  unless otherwise noted)



## ➤ Package Information



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